

2.0x1.25mm BI-COLOR SMD CHIP LED LAMP



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: APB2012QBDCGKC

Blue Green

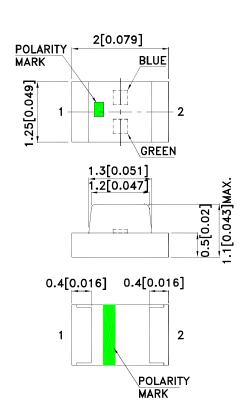
Features

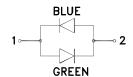
- 2.0mmx1.25mm SMT LED, 1.1mm thickness.
- Bi -color,Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

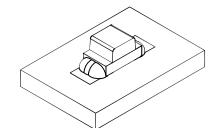
Descriptions

- The Blue source color devices are made with InGaN Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- Electrostatic discharge and power surge could damage
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APB2012QBDCGKC	Blue (InGaN)	Water Clear	40	80	150°
	Green (AlGalnP)	Water Clear	20	50	

Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue Green	460 574		nm	IF=20mA
λD [1]	Dominant Wavelength	Blue Green	465 570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue Green	25 20		nm	IF=20mA
С	Capacitance	Blue Green	100 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue Green	3.3 2.1	4 2.5	V	IF=20mA

Notes:

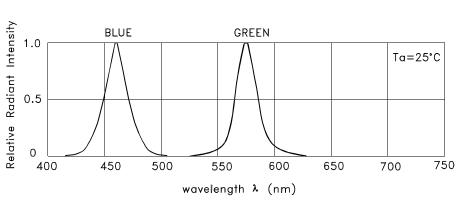
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Green	Units		
Power dissipation	120	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	150	150	mA		
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

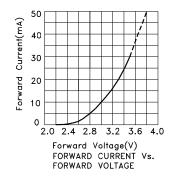
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

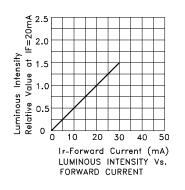
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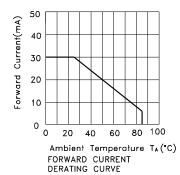


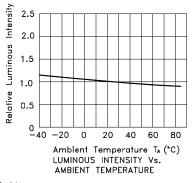
RELATIVE INTENSITY Vs. WAVELENGTH

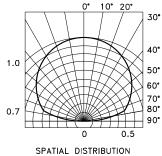
APB2012QBDCGKC Blue





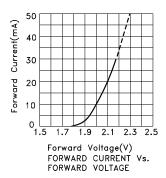


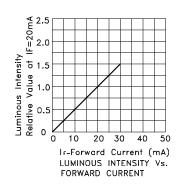


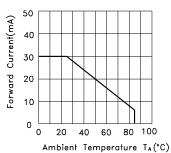


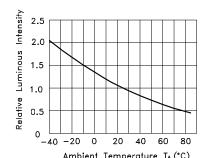
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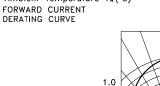
Green



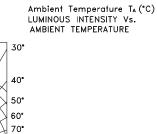








0.7



80°

90°

SPATIAL DISTRIBUTION

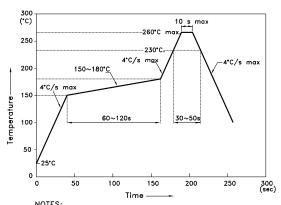
10° 20°

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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



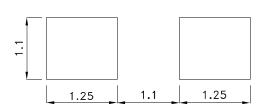
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

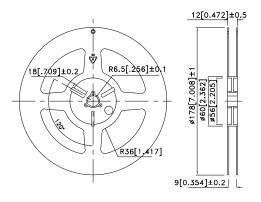
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

 3.Number of reflow process shall be 2 times or less.

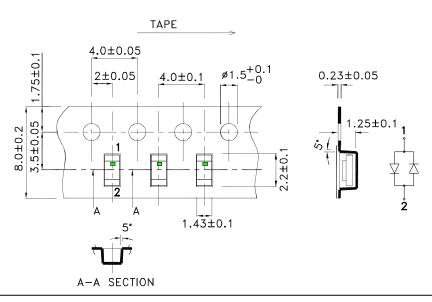
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Reel Dimension



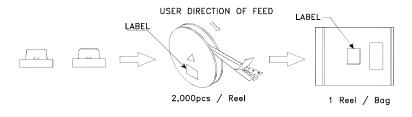
Tape Dimensions (Units : mm)

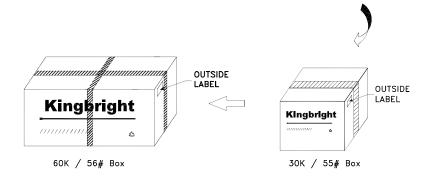


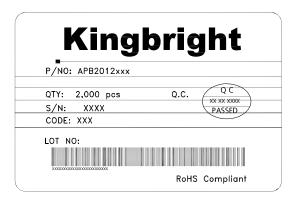
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PACKING & LABEL SPECIFICATIONS

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